


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	ADG/19/11732	
1.3 Title of PCN	I2PAK, TO-220, TO-247 New Molding Compound Shenzhen (China) - Bouskoura (Marocco) AUTOMOTIVE	
1.4 Product Category	Power MOSFET Power BIPOLAR	
1.5 Issue date	2019-08-30	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	NEMETH KRISZTINA
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Mario ASTUTI,Maurizio GIUDICE,Angelo RAO,Nicola LIPORACE
2.1.2 Marketing Manager	Anna MOTTESE,Michele SCUTO,Giuseppe BAZZANO
2.1.3 Quality Manager	Vincenzo MILITANO,Francesco MINERVA

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Mold compound	BOUSKOURA B/E (Morocco) SHENZHEN (China)

4. Description of change

	Old	New
4.1 Description	Samsung SDI product termination of the following references of molding compound for I2PAK, TO-220, TO-247 packages.	Replacement of current mold compounds with alternative material. ST is already proceeding with new resins evaluation and qualification, to guarantee adequate products continuity.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impacts	

5. Reason / motivation for change

5.1 Motivation	Product discontinuance from current supplier
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	by FG code and Q.A. number
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7. Timing / schedule

7.1 Date of qualification results	2019-08-22
7.2 Intended start of delivery	2020-03-30
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	11732 Rel18-2019.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2019-08-30

9. Attachments (additional documentations)

11732 Public product.pdf
11732 New Molding compound - AUT.pdf
11732 Rel18-2019.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
BU931P	BU931P	
	STW65N65DM2AG	

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Public Products List

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PCN Title : I2PAK, TO-220, TO-247 New Molding Compound Shenzhen (China) - Bouskoura (Marocco) AUTOMOTIVE

PCN Reference : ADG/19/11732

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STP315N10F7	STI47N60DM6AG	STP120N4F6
STP100NF04	STW58N60DM2AG	STW19NM60N
STW65N65DM2AG	STW78N65M5	STP180NS04ZC
STP80NF55-08AG	STP95N4F3	STP45N40DM2AG
STW50N65DM2AG	STW36N60DM6AG	STI270N4F3
STW47N60DM6AG	STP150NF55	STP80NF55-08
STP410N4F7AG	STI55NF03L	STW58N65DM2AG
BU941ZT	STI300N4F6	STP141NF55
STW22N95K5	BU931P	STB130NS04ZB-1
STW46NF30	STB80NF55-06-1	STW62N65M5
STP76NF75	STP85NF55	STW72N60DM2AG
STP36NF06L	BU931T	STW37N60DM2AG
STI76NF75	STP185N55F3	STP46NF30
STW45N60DM2AG	STP150NF04	STP80N6F6
STP190N55LF3	STP45N60DM2AG	



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